

Α

5

TOP VIEW

FRONT VIEW

В

aaa C

SEE DETAIL 'A'

2X



TERMINAL #1

INDEX AREA

(D/2 X E/2)

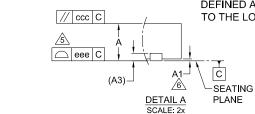
☐ aaa C

WDFN8 3.30x3.30x0.75, 0.65P CASE 483AW ISSUE B

DATE 22 MAR 2024

NOTES:

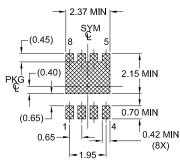
- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JEP95 SEC. 3 SPP-12. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD, EMBEDDED METAL OR MARKED FEATURE.
- ©COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
- SEATING PLANE IS DEFINED BY THE TERMINALS. 'A1' IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



bbb(M) C A B e1 - L (4x) b (8X) - E2 - L (4x)

BOTTOM VIEW

LAND PATTERN RECOMMENDATION



*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

DIM	MILLIMETERS			
	MIN	NOM	MAX	
Α	0.70	0.75	0.80	
A1			0.05	
A3	0.20 REF			
b	0.27	0.32	0.37	
D	3.30 BSC			
D2	2.17	2.27	2.37	
E	3.30 BSC			
E2	1.56	1.66	1.76	
е	0.65 BSC			
e1	1.95 BSC			
K	0.90			
L	0.30	0.40	0.50	
aaa	0.10			
bbb	0.10			
ccc	0.10			
ddd	0.05			
eee	0.05			

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code A = Assembly Location

Y = Year

WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WDFN8 3.30x3.30x0.75, 0.65P		PAGE 1 OF 1	

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